

Abstract

The present invention relates to a mold releasing film for printed circuit board production, which

5 comprises a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more. According to the present invention, it is possible to provide a mold releasing film suitable for production of printed circuit boards, particularly flexible printed

10 circuit boards, which is excellent in mold-releasing property, exhibits little heat shrinkage, hardly imparts wrinkles to printed circuit board products, itself hardly gets wrinkled, and is excellent in contamination resistance since no bleeding-out is observed, and which

15 is also excellent in an anti-moisture absorbing property, shape-following property, less overflow of adhesive, adhesion between multilayer films and slipping property between films.